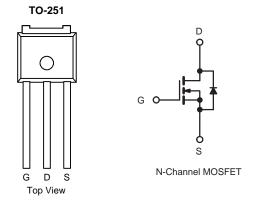


N-Channel 30-V (D-S) MOSFET

| PRODUCT SUMMARY | | | | | | |
|---------------------|---------------------------------|--------------------|-----------------------|--|--|--|
| V _{DS} (V) | $R_{DS(on)}\left(\Omega\right)$ | I _D (A) | Q _g (Typ.) | | | |
| 30 | 0.07 at V _{GS} = 10 V | 53 | 19 nC | | | |
| | 0.09 at V _{GS} = 4.5 V | 48 | 19110 | | | |



FEATURES

- Halogen-free
- TrenchFET® Gen III Power MOSFET
- 100 % R_g Tested 100 % UIS Tested

APPLICATIONS

- DC/DC Conversion
 - System Power

| Parameter | Symbol Limit | | Unit | | |
|---|------------------------|-----------------------------------|---------------------|----|--|
| Drain-Source Voltage | | V _{DS} | 30 | V | |
| Gate-Source Voltage | | V_{GS} | ± 20 | | |
| | T _C = 25 °C | | 53 | | |
| Continuous Drain Current (T _{.1} = 150 °C) | T _C = 70 °C | I | 41 | | |
| Continuous Dialii Current (1 j = 150 °C) | T _A = 25 °C | - I _D | 14 ^{b, c} | Α. | |
| | T _A = 70 °C | | 10 ^{b, c} | ^ | |
| Pulsed Drain Current | | I _{DM} | 165 | | |
| Avalanche Current | L = 0.1 mH | I _{AS} | 25 | | |
| Avalanche Energy | L = 0.1 11111 | E _{AS} | 40 | mJ | |
| Continuous Source-Drain Diode Current | T _C = 25 °C | 1- | 15 | A | |
| Continuous Source-Diam Diode Current | T _A = 25 °C | ls ==== | 2.9 ^{b, c} | | |
| | T _C = 25 °C | | 28 | | |
| Maximum Power Dissipation | T _C = 70 °C | P _D | 18 | W | |
| Maximum Power Dissipation | T _A = 25 °C | LD | 3.5 ^{b, c} | VV | |
| | T _A = 70 °C | | 2.2 ^{b, c} | | |
| Operating Junction and Storage Temperature Range | | T _J , T _{stg} | - 55 to 150 | °C | |
| Soldering Recommendations (Peak Tempera | | 260 | | | |

| THERMAL RESISTANCE RATINGS | | | | | | | |
|----------------------------------|--------------|-------------------|---------|---------|---------|--|--|
| Parameter | | Symbol | Typical | Maximum | Unit | | |
| Maximum Junction-to-Ambient | t ≤ 10 s | R _{thJA} | 29 | 36 | °C/W | | |
| Maximum Junction-to-Case (Drain) | Steady State | R _{thJC} | 3.6 | 4.5 |] 5/ ** | | |

- a. Based on T_C = 25 °C.
 b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 10 s.



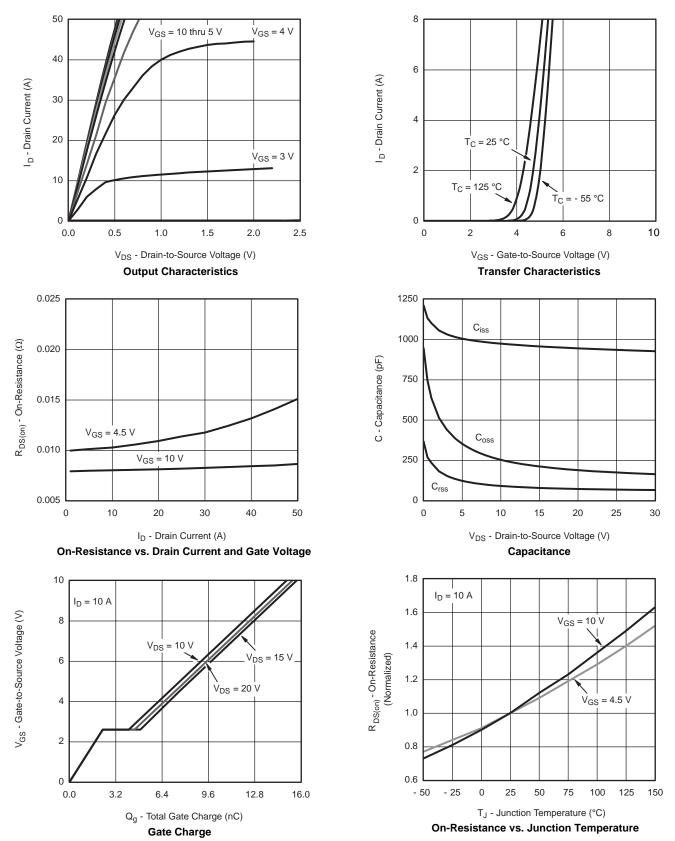
| Parameter | Symbol | Test Conditions | Min. | Тур. | Max. | Unit |
|---|---------------------------------------|--|------|-------|-------|---------|
| Static | | | I. | • | I. | |
| Drain-Source Breakdown Voltage | V _{DS} | $V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$ | 30 | | | V |
| V _{DS} Temperature Coefficient | $\Delta V_{DS}/T_J$ $I_D = 250 \mu A$ | | | 33 | | mV/°C |
| V _{GS(th)} Temperature Coefficient | $\Delta V_{GS(th)}/T_J$ | I _D = 250 μA | | - 5 | | mv/°C |
| Gate-Source Threshold Voltage | V _{GS(th)} | $V_{DS} = V_{GS}$, $I_{D} = 250 \mu A$ | 1.2 | | 3.0 | V |
| Gate-Source Leakage | I _{GSS} | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$ | | | ± 100 | nA |
| | I _{DSS} | V _{DS} = 30 V, V _{GS} = 0 V V _{DS} = 30 V, V _{GS} = 0 V, T _J = 55 °C | | | 1 | μΑ |
| Zero Gate Voltage Drain Current | | | | | 5 | |
| On-State Drain Current ^a | I _{D(on)} | $V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$ | 15 | | | Α |
| Danis Common Co Oloto Donisto and | | $V_{GS} = 10 \text{ V}, I_D = 10 \text{ A}$ | | 0.070 | | |
| Drain-Source On-State Resistance ^a | R _{DS(on)} | $V_{GS} = 4.5 \text{ V}, I_{D} = 7 \text{ A}$ | | | | Ω |
| Forward Transconductance ^a | g _{fs} | V _{DS} = 15 V, I _D = 10 A | | 24 | | S |
| Dynamic ^b | | | I. | • | | |
| Input Capacitance | C _{iss} | | | 1400 | | pF |
| Output Capacitance | C _{oss} | $V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$ | | 200 | | |
| Reverse Transfer Capacitance | C _{rss} | | | 150 | | |
| Total Cata Chausa | 0 | $V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 10 \text{ A}$ | | 33 | | nC |
| Total Gate Charge | Q _g | | | 18 | | |
| Gate-Source Charge | Q _{gs} | $V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 10 \text{ A}$ | | 7.3 | | |
| Gate-Drain Charge | Q _{gd} | | | 6.2 | | |
| Gate Resistance | R_g | f = 1 MHz | 0.2 | 0.8 | 1.6 | Ω |
| Turn-On Delay Time | t _{d(on)} | | | 15 | 30 | |
| Rise Time | t _r | V_{DD} = 15 V, R_L = 1.5 Ω | | 12 | 24 | |
| Turn-Off Delay Time | t _{d(off)} | $I_D\cong$ 10 A, V_{GEN} = 4.5 V, R_g = 1 Ω | | 13 | 26 | |
| Fall Time | t _f | | | 10 | 20 | |
| Turn-On Delay Time | t _{d(on)} | | | 9 | 18 | ns - |
| Rise Time | t _r | V_{DD} = 15 V, R_L = 1.5 Ω | | 9 | 18 | |
| Turn-Off Delay Time | t _{d(off)} | $I_D\cong 10$ A, $V_{GEN}=10$ V, $R_g=1$ Ω | | 14 | 28 | |
| Fall Time | t _f | | | 8 | 16 | |
| Drain-Source Body Diode Characteristi | cs | | I. | • | | |
| Continuous Source-Drain Diode Current | I _S | $T_C = 25 ^{\circ}C$ | | | 16 | ۸ |
| Pulse Diode Forward Current | I _{SM} | | | | 32 | Α |
| Body Diode Voltage | V_{SD} | I _S = 3 A, V _{GS} = 0 V | | 0.78 | 1.2 | V |
| Body Diode Reverse Recovery Time | t _{rr} | | | 17 | 34 | ns |
| Body Diode Reverse Recovery Charge | Q _{rr} | L = 10 A dl/dt = 100 A/up T = 25 °C | | 9.5 | 19 | nC |
| Reverse Recovery Fall Time | t _a | $I_F = 10 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$ | | 10 | | |
| Reverse Recovery Rise Time | t _b | | | 7 | | ns |

Notes:

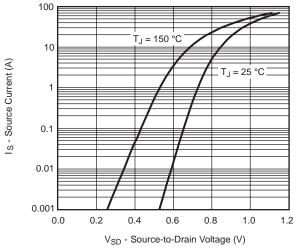
- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

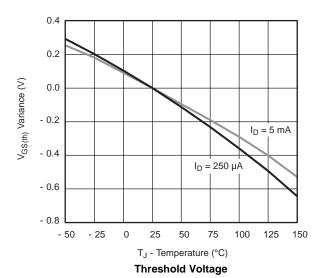


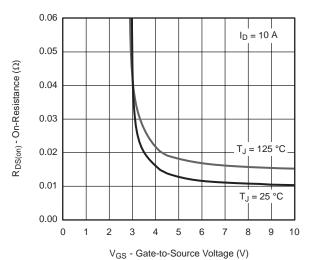




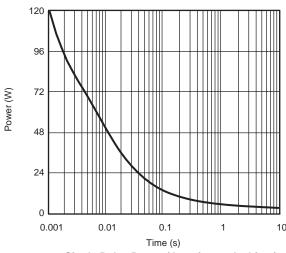


Source-Drain Diode Forward Voltage

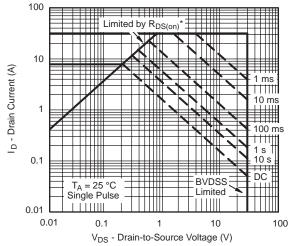




On-Resistance vs. Gate-to-Source Voltage



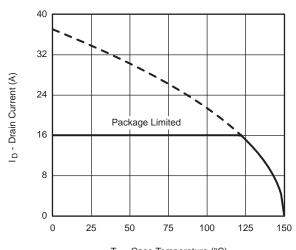
Single Pulse Power (Junction-to-Ambient)



* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

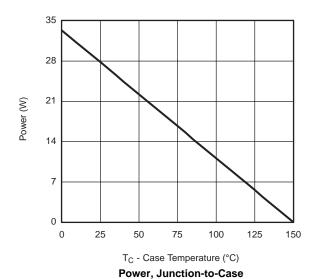
Safe Operating Area, Junction-to-Ambient

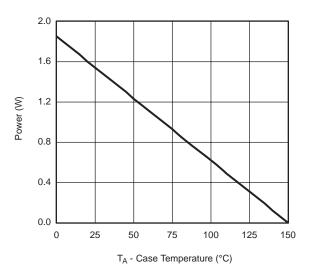




T_C - Case Temperature (°C)

Current Derating*

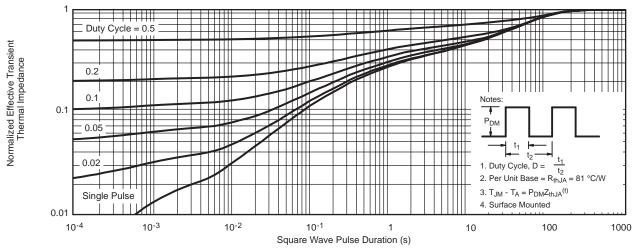




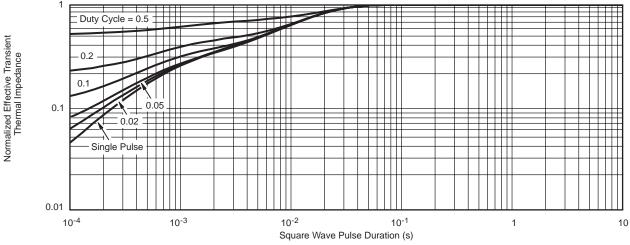
Power, Junction-to-Ambient

^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





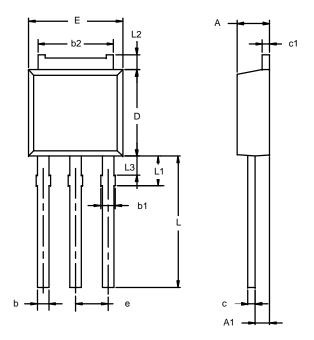
Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case



TO-251AA (DPAK)



Note: Dimension L3 is for reference only.

| | MILLIM | IETERS | INC | HES | | |
|---|----------|--------|-------|-----------|--|--|
| Dim | Min | Max | Min | Max | | |
| Α | 2.21 | 2.38 | 0.087 | 0.094 | | |
| A 1 | 0.89 | 1.14 | 0.035 | 0.045 | | |
| b | 0.71 | 0.89 | 0.028 | 0.035 | | |
| b1 | 0.76 | 1.14 | 0.030 | 0.045 | | |
| b2 | 5.23 | 5.43 | 0.206 | 0.214 | | |
| С | 0.46 | 0.58 | 0.018 | 0.023 | | |
| с1 | 0.46 | 0.58 | 0.018 | 0.023 | | |
| D | 5.97 | 6.22 | 0.235 | 0.245 | | |
| Е | 6.48 | 6.73 | 0.255 | 0.265 | | |
| е | 2.28 BSC | | 0.090 | 0.090 BSC | | |
| L | 3.89 | 9.53 | 0.153 | 0.375 | | |
| L1 | 1.91 | 2.28 | 0.075 | 0.090 | | |
| L2 | 0.89 | 1.27 | 0.035 | 0.050 | | |
| L3 | 1.15 | 1.52 | 0.045 | 0.060 | | |
| ECN: S-03946—Rev. E, 09-Jul-01 DWG: 5346 | | | | | | |



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